

HiDECK® Overlay 18

High Density Overlay Board for Under Floor Heating Applications



Product Information

HiDECK Overlay 18 is ideal for flooring applications incorporating an underfloor heating system due to its high thermal conductivity which provided rapid reaction times, saving on running costs. In addition, It's high density makes it perfect for a variety of acoustic applications.

Product Benefits

- ◻ Low thermal resistance - Perfect for UFH applications
Robust Detail treatment **FFT4** compliant
- ◻ Suitable for all types of steel, concrete and timber floors
- ◻ Feels like screed
- ◻ Directly accepts all types of floor covering, inc. tiles

Technical Information

		HiDECK Overlay 18
Product description	-	Low thermal resistance overlay floorboard
Thickness	mm	18
Type and composition	-	Tongue & groove high density gypsum
Thermal resistance	m ² /kW	0.045
Board dimensions	mm	600 x 1200
Weight	kg/m ² kg/board	21.60 15.55
Associated flanking strip required	-	YELOfon FS50, ES5/100



Third Party Accreditation and Approvals



Environmental Credentials

